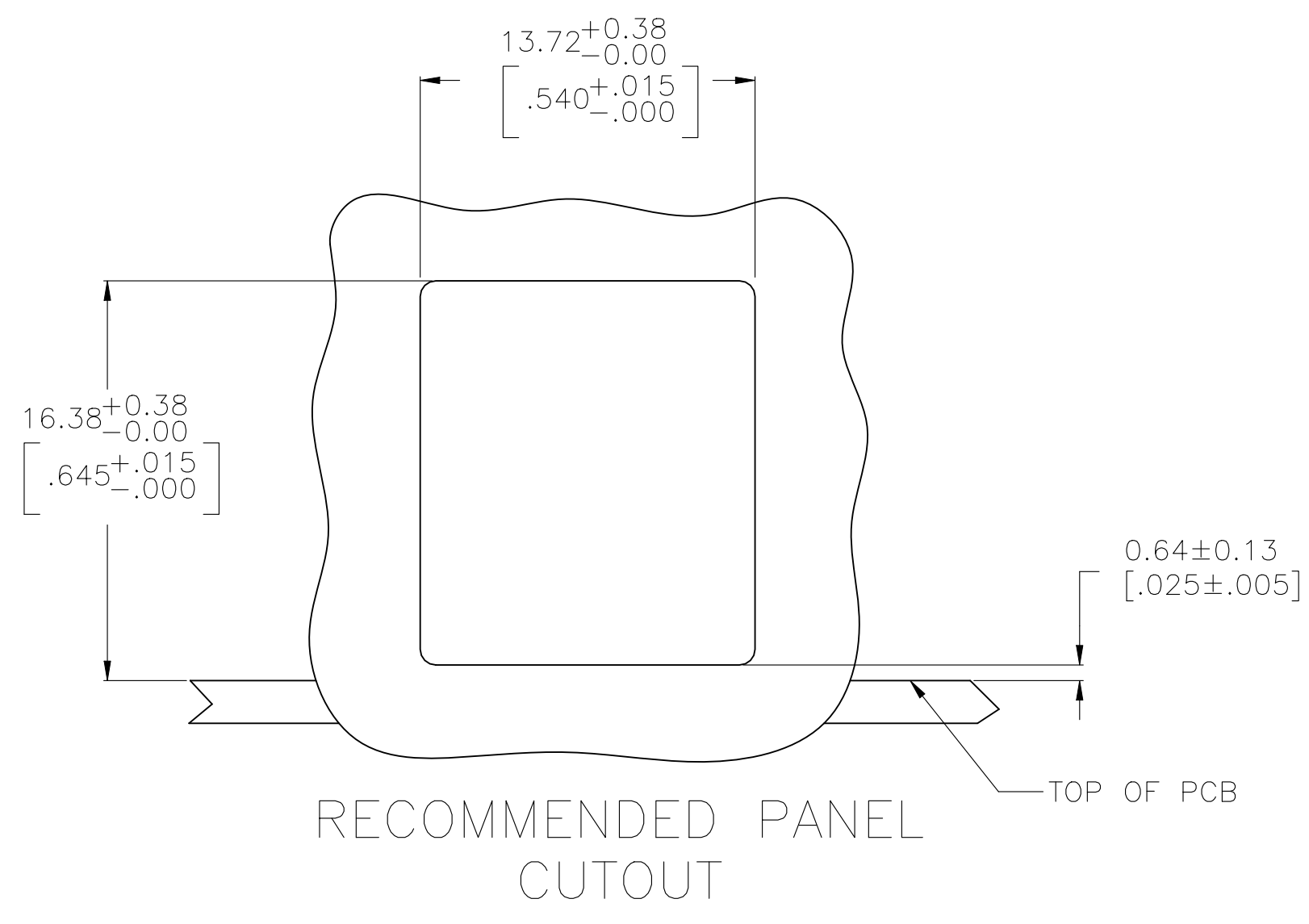
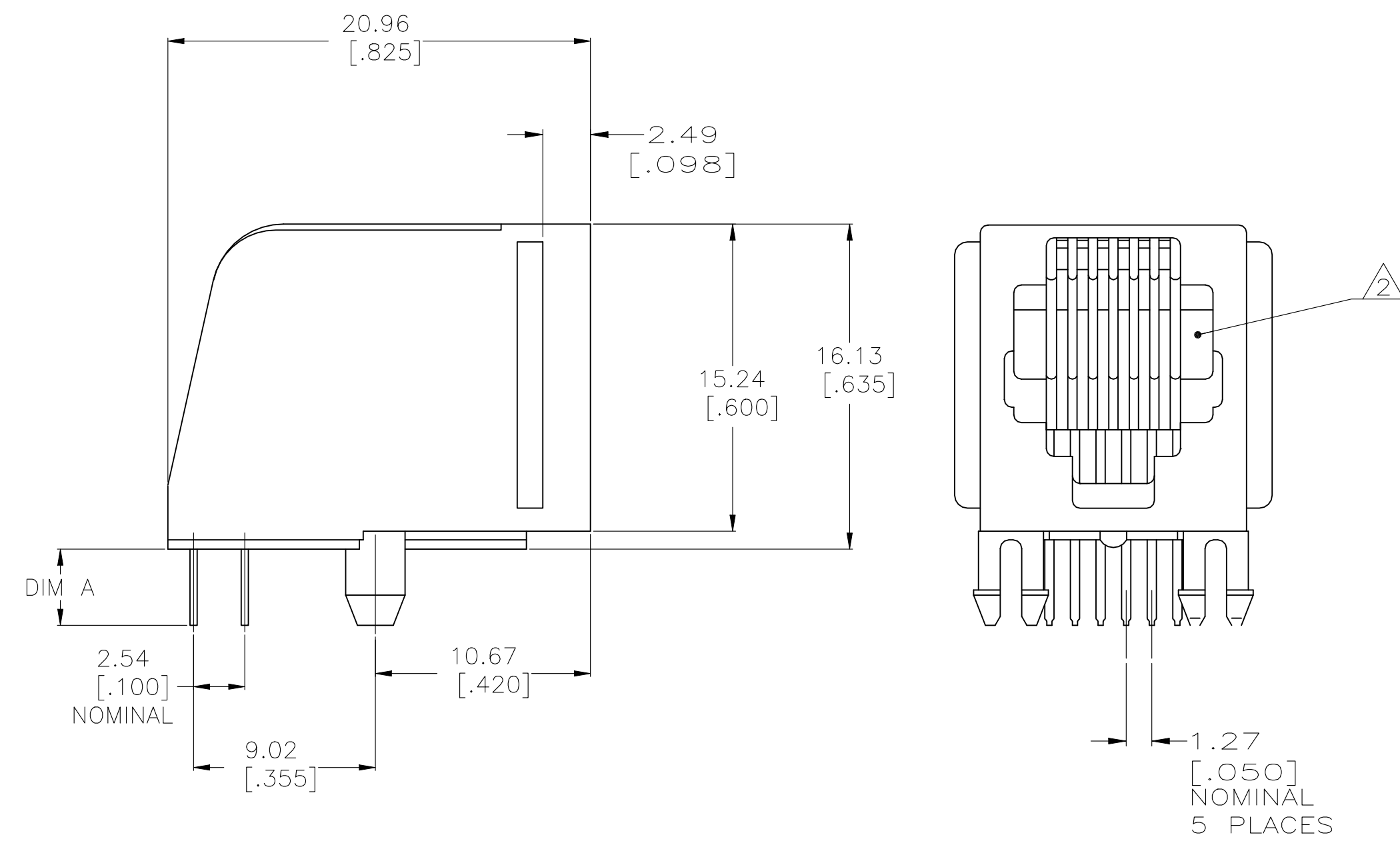
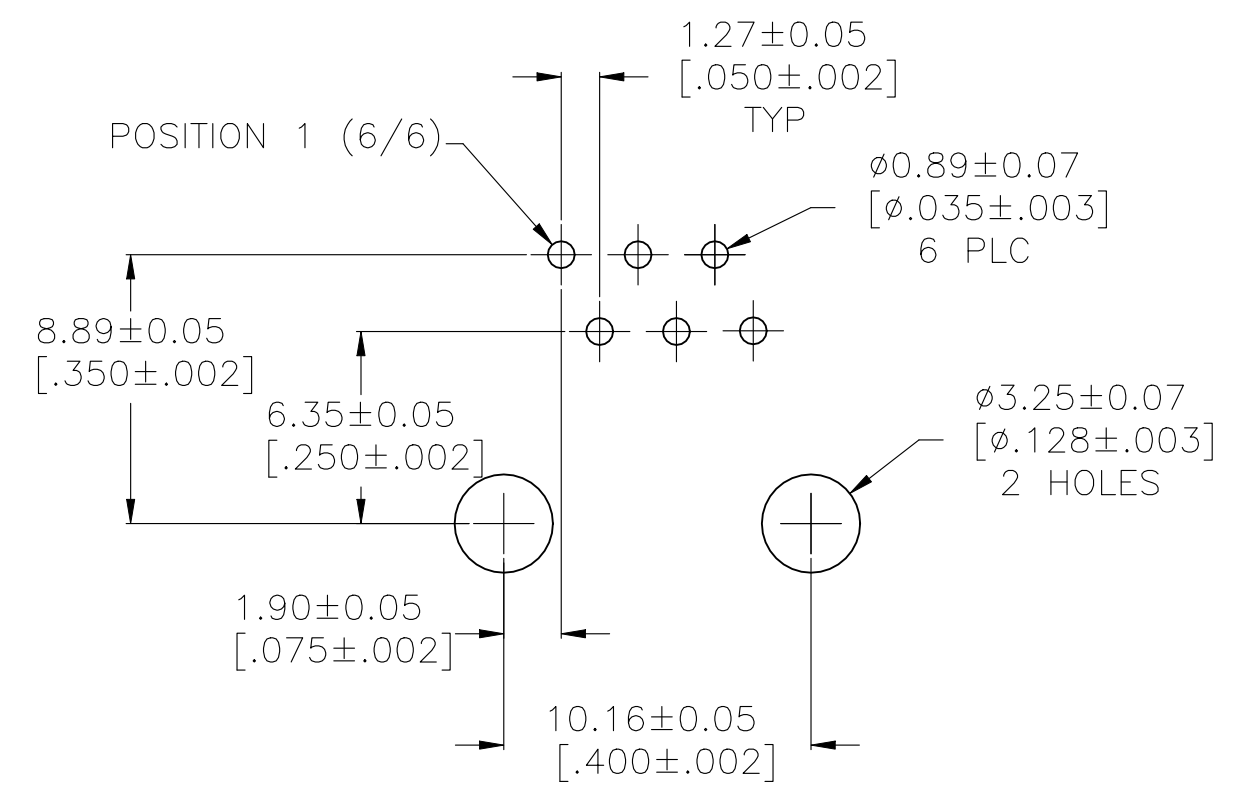
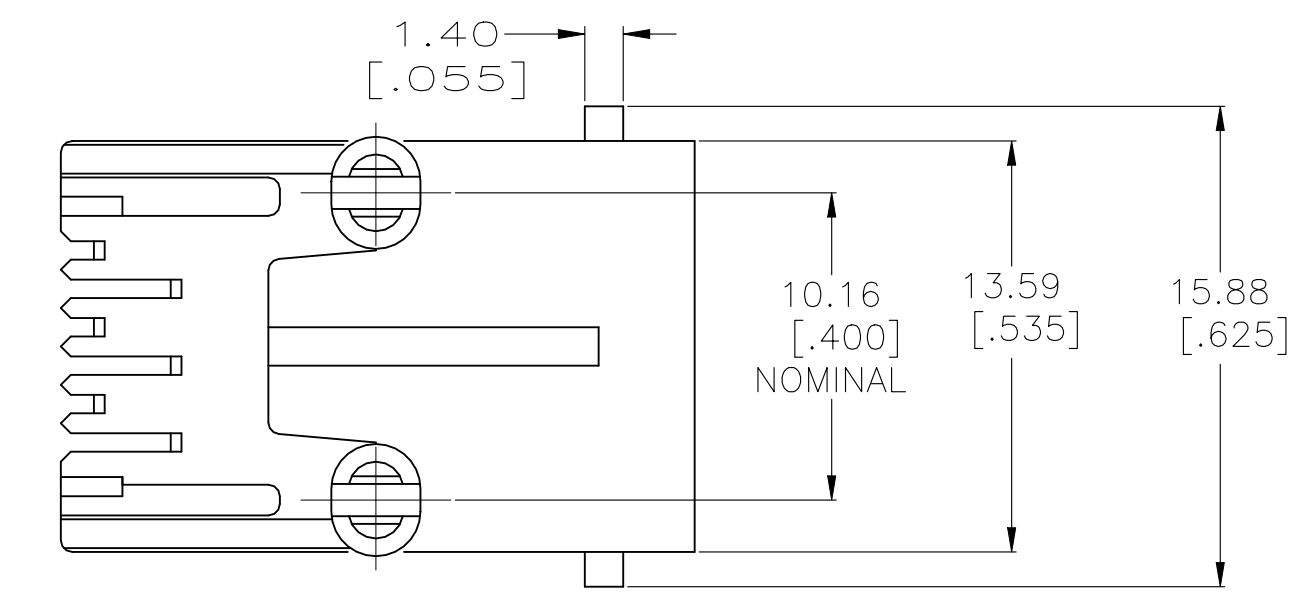


REVISIONS					
REV	DATE	DESCRIPTION	BY	CHK	APP'D
D3	07NOV2022	REVISED AS PER ECN-22-180673	KH	SZ	



- MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH (SEE TABLE) MIN HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm[.000080] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 0.15µm[.000006] GOLD PLATED PARTS DO NOT MEET THE MINIMUM GOLD THICKNESS REQUIREMENT OF FCC SPECIFICATION, PART 68. PARTS HAVE NOT BEEN TESTED TO THE DURABILITY REQUIREMENTS OF TE PRODUCT SPEC 108-1163
- TERMINALS FOR 5520250-1 AND -2 LOCATED IN CENTER POSITIONS
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

OBSOLETE	0.15µm[.000006]	3.30-4.32 [.130-.170]	6	2-5520250-3
			4	2-5520250-2
		2.16-2.67 [.085-.105]	4	1-5520250-1
OBSOLETE	1.27µm[.000050]	3.30-4.32 [.130-.170]	6	5520250-3
			4	5520250-2
			2	5520250-1
	GOLD THICKNESS	DIM A	TERMINALS REQUIRED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN 12MAY2005	T. WOOTEN/LA.MAYER
0 PLC ± -	1 PLC ± -	12MAY2005	J.WESTMAN
2 PLC ± 0.13[.005]	3 PLC ± -	12MAY2005	S.FLICKINGER
4 PLC ± -	ANGLES ± -	NAME	TE Connectivity
SEE NOTE 1	SEE NOTE 1	PRODUCT SPEC	MODULAR JACK ASSEMBLY, 6 POSITION, SIDE ENTRY, FLANGELESS, WITH PANEL STOPS
		APPLICATION SPEC	108-1163
		SIZE	114-2048
		WEIGHT	0.000000
		SCALE	4:1
		SHEET	1 of 1
		REV	D3